

(1,00mm) .03937"

MEC1 SERIES

MEC1-120-02-F-D-A

MEC1-130-02-F-D-A

MEC1-140-02-L-D

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material: Black LCP

Contact Material: BeCu

Plating: Sn or Au over 50µ"

(1,27µm) Ni

Operating Temp Range: -55°C to +125°C

Current Rating: 2A @ 80°C ambient

(See website for details)

Voltage Rating: 300 VAC

Insertion Depth: (5,84mm) .230" to

(8,13mm) .320"

RoHS Compliant: Yes

Processing: Lead-Free Solderable:

Yes

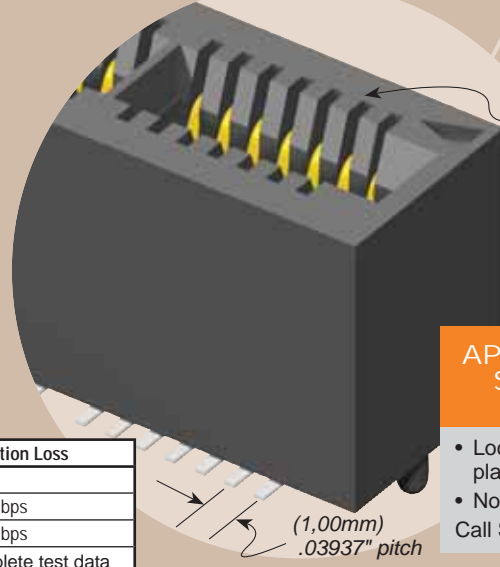
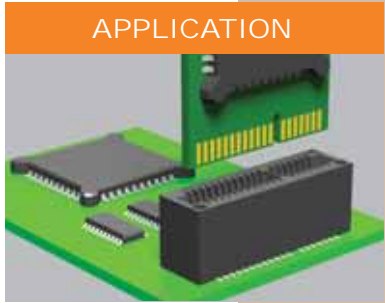
SMT Lead Coplanarity: (0,10mm) .004" max (05-20)

(0,15mm) .006" max (30-70)



Mates with: (1,60mm) .062" card

APPLICATION



Mates with (1,60mm) .062" card

APPLICATION SPECIFIC OPTION

- Locking Clip (Manual placement required).
- Non-polarized Call Samtec.

| 1mm MEC1 | Rated @ -3dB Insertion Loss |
|-----------------------------|-----------------------------|
| 9,19mm Stack Height | |
| Single-Ended Signaling | 5.5 GHz / 11 Gbps |
| Differential Pair Signaling | 6.5 GHz / 13 Gbps |

Performance data for other stack heights and complete test data available at www.samtec.com?MEC1 or contact sig@samtec.com



05, 08, 20, 30, 40, 50, 60, 70

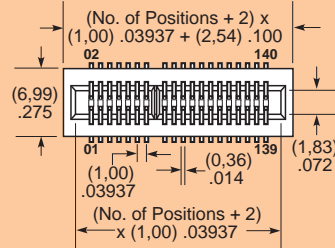
-F
= Gold flash on contact, Matte tin on tail

-L
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

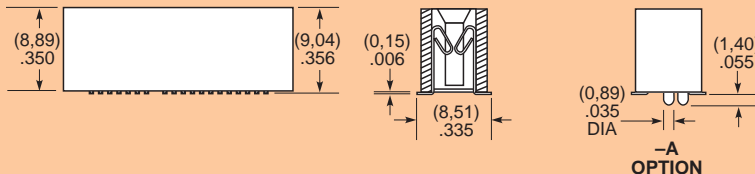
-A
= Alignment Pin metal or plastic at Samtec discretion.

-K
= (7,87mm) .310" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel



| POSITIONS PER ROW | POLARIZED POSITIONS (No Contact) |
|-------------------|----------------------------------|
| 05 | 3, 4 |
| 08 | 5, 6 |
| 20 | 15, 16 |
| 30 | 21, 22 |
| 40 | 31, 32 |
| 50 | 41, 42 |
| 60 | 31, 32, 63 & 64 |
| 70 | 53, 54, 115 & 116 |



Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM